



Material declaration form

General Information						
IPC	1752	Version	2			
Form type*	Distribute	Version	2			
Sectionals*	Material information	Subsectionals*	A-D			
	Manufacturing information	*: Required Field				

Supplier Information							
Company name*	STMicroelectronics	Response Date*	2025-08-07				
Contact name*	Refer to Supplier Comment section		Refer to Supplier Comment section				
Contact phone*	Refer to Supplier Comment section	Contact email*	Refer to Supplier Comment section				
Authorized representative*	MDRF CHAMPION	Representative title	MDRFMaterial Declaration champion				
Representative phone*	Refer to Supplier Comment section	Representative email*	Refer to Supplier Comment section				
Supplier comment	Online Technical Support - STMicroelectron http://www.st.com/web/en/support/support.h						

Uncertainty statement

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Legal statement Supplier acceptance* true Legal declaration* Standard

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

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Product								
Mfr item number	Mfr item name	Version	Manufacturing site	date				
STM32F205RFT6	STM32F205RFT6 625W*411XXX5		998Z	2025-08-07				
	Amount	Unit of measure	Unit type	ST ECOPACK grade				
	359	mg	Each	ECOPACK® 2				

Manufacturing information							
J-STD-020 MSL rating	Classification temperature	Number of reflow cycles					
3	260	3					
Bulk solder termination	Terminal plating	Terminal base alloy	Comment				
Not Applicable	Tin (Sn), matte	Copper Alloy	0				
Package designator	Package size	Number of instances	Shape				
QFP	10x10	64	Gull wing				
Comment	Package : 5W LQFP 64 10x10x1.4 1 0051434						

QueryList: RoHS Directive 2011/65/EU- 8 June 2011 – Annex II amended by Delegated Directive 2015/863 - 31 March 2015 Response						
1 - Product(s) meets EU RoHS requireme	true					
2 - Product(s) meets EU RoHS requireme apply)	false					
3 - Product(s) meets EU RoHS requireme	false					
4 - Product(s) does not meet EU RoHS re	false					
Exemption Id.	Description					
,						

QueryList : REACH-25th June 2025	Response			
1 - Product(s) does not contain REACH S	true			
CategoryLevel_Name CategoryLevel_Threshold		amount in product (mg)	Application	ppm in product
,	#N/A			

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Material Composition Declaration: note: Substance present with less 0.001mg will not be declared in this document					Mfr Item Name	625W°411XXX5		359.067		6000000	1000000	
Homogeneous material	Material group	Mass	Unit of measure	Level	Substance category	Substance	CAS	Exempt	Mass	Unit of measure	Concentration in homogeneous material (ppm)	Concentration i
Die ordies	M-011 Other inorganic materials	14.626	mg	supplier	die	Silicon (Si)	7440-21-3		13.630	mg	931916	37960
				supplier	metallization	Aluminium (AI)	7429-90-5		0.070	mg	4792	195
				supplier	metallization	Copper (Cu)	7440-50-8		0.453	mg	30947	1261
				supplier	metallization	Cobalt (Co)	7440-48-4		0.001	mg	100	4
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.063	mg	4293	175
				supplier	metallization	Tungsten (W)	7440-33-7		0.203	mg	13876	565
				supplier	Passivation	Silicon Nitride	12033-89-5		0.053	mg	3594	146
				supplier	Passivation	Silicon Oxide	7631-86-9		0.153	mg	10482	427
Glue epoxy (EN4900GC)	Other Organic Materials	0.755	mg	supplier	Organic Compounds	Acrylic resin	Proprietary		0.053	mg	70000	147
				supplier	Organic Compounds	Polybutadiene derivative	Proprietary		0.015	mg	20000	42
				supplier	Organic Compounds	Butadiene copolymer	Proprietary		0.011	mg	15000	32
				supplier	Organic Compounds	Acrylate	Proprietary		0.041	mg	54000	113
				supplier	Organic Compounds	Epoxy resin	Proprietary		0.023	mg	30000	63
				supplier	Organic Compounds	Peroxide	Proprietary		0.006	mg	8000	17
				supplier	Organic Compounds	Additive	Proprietary		0.014	mg	18000	38
				supplier	Metals	Silver	7440-22-4		0.592	mg	785000	1650
Encapsualtion (EME-G700LAL-A)	Other Organic Materials	237.015	mg	supplier	Organic Compounds	Epoxy Resin	Proprietary		13.036	mg	55000	36305
				supplier	Organic Compounds	Phenol Resin	Proprietary		4.977	mg	21000	13862
				supplier	Glass	Silica(Amorphous)A	60676-86-0		189.612	mg	800000	528069
				supplier	Glass	Silica(Amorphous)B	7631-86-9		28.205	mg	119000	78550
				supplier	Organic Compounds	Carbon Black	1333-86-4		1.185	mg	5000	3300
Bonding wire (Cu)	Bonding Wire	0.933	mg	supplier	Metals	Copper	7440-50-8		0.901	mg	965500	2509
				supplier	Metals	Palladium	7440-05-3		0.029	mg	31000	81
				supplier	Metals	Gold	7440-57-5		0.003	mg	3500	9
Plating anode (Sn)	Other inorganic materials	1.438	mg	supplier	Metals	Tin	7440-31-5		1.438	mg	1000000	4004
Leadframe (C7025 + Ag)	Copper & its alloys	104.300	mg	supplier	Metals	Copper	7440-50-8		101.536	mg	973499	282777
				supplier	Metals	Iron	7439-89-6		2.377	mg	22790	6620
				supplier	Metals	Phosphor	7723-14-0		0.026	mg	250	73
				supplier	Metals	Zinc	7440-66-6		0.131	mg	1260	366
				supplier	Metals	Siliver	7440-22-4		0.229	mg	2200	639
				SVHC	Metals	Lead	7439-92-1		0.000	mg	1	0

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